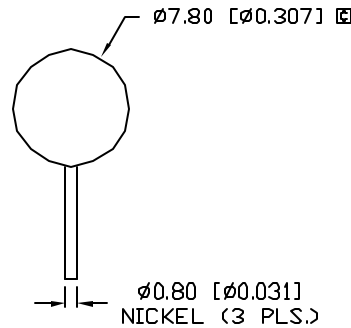
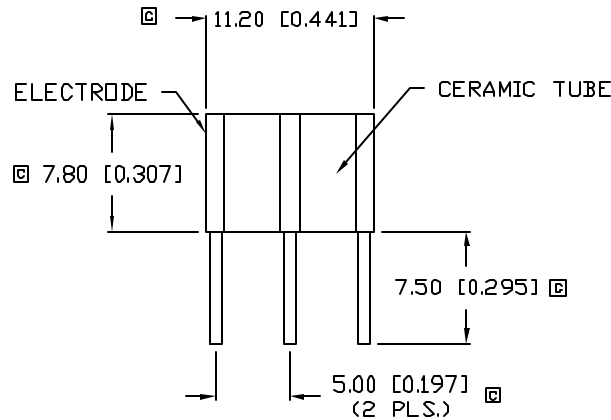


UNCONTROLLED DOCUMENT

PART NUMBER  
GT-CM3090L

REV.  
D

A	E.C.N. #10107./	12-22-95
B	E.C.N. #10BRDR. & REDRAWN.	8-20-99
C	E.C.N. #10BRDR. & 10912.	9.23.02
D	E.C.N. #11148.	12.11.06



ELECTRICAL SPECIFICATIONS

PARAMETER	VALUE	TEST CONDITION
D.C. FIRING VOLTAGE:	90V±20% D.C.	(dv/dt 100V/S)
IMPULSE FIRING VOLTAGE:	450V D.C. MAX.	(dv/dt 100V/μS)
IMPULSE CURRENT:	10KA MAX.	(B/20μS)
D.C. HOLDOVER VOLTAGE:	50V D.C. MAX.	(10/1000μS 500A)
A.C. DISCHARGE CURRENT:	65A	(50Hz, 9 CYCLES)
INSULATION RESISTANCE:	10 <sup>4</sup> MΩ MIN.	(50 OR 100VDC)
INTER-ELECTRODE CAPACITANCE:	2.0 PF MAX.	1.0kHz

ENVIRONMENTAL SPECIFICATIONS PER MIL-STD 202

TEST	METHODE	CONDITION	RATING
VIBRATION TESTING:	204B	C	10-55HZ, .06DA
SHOCK	213A	C	100G
HUMIDITY:	103B	B	95%RH HUMIDITY
TEMPERATURE CYCLING:	102A	C	- 65 TO + 125 °C
BAROMETRIC PRESSURE:	105C	B	50,000FT.
THERMAL SHOCK:	107	B	- 65 TO + 125 °C
SOLDERABILITY:	20B	B	

RESPONSE TIME

SURGE TYPE	(RI MAX.)
1Kv/mS	1 x 10 <sup>-5</sup> sec.
1Kv/μS	1 x 10 <sup>-8</sup> sec.
5Kv/μS	1 x 10 <sup>-9</sup> sec.

NOTES:

1. CENTER TO CENTER LEAD SPACING IS MEASURED AT 1.0mm FROM BOTTOM OF THE CERAMIC BODY.

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005), LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

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REV. D	PART NUMBER GT-CM3090L
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T8 x 11 CERAMIC ARRESTOR, 3 LEADED, 90V DC.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: jc	CHECKED BY:	APPROVED BY:	DATE: 12.11.06 PAGE: 1 OF 1 SCALE: N/A
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